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# J Std 003c

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July 9th, 2018 - J STD 003 Solderability Tests for Printed Boards is the defining standard prescribing test methods defect definitions and illustrations for assessing the solderability of printed board surface conductors attachment lands and plated through holes utilizing either tin lead or lead free solders"**IPC J STD 003C WAM1 Solderability Tests for Printed Boards**  
**July 8th, 2018 - J STD 003C prescribes test methods defect definitions and illustrations for assessing the solderability of printed board surface conductors attachment lands and plated through holes utilizing either tin lead or lead free solders'**  
**'J STD 033C standard JEDEC**  
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July 6th, 2018 - IPC J STD 003C WAM1 amp 2 standard prescribes test methods defect definitions and illustrations for assessing the solderability of printed board surface conductors attachment lands and plated through holes PTHs'

'IPC J STD 003C Solderability Tests for PCB

June 24th, 2018 - EpP Forum Elettronica per Passione Generato 23 June 2018 04 47 IPC J STD 003C Solderability Tests for PCB Scritto da MdL 02 10 2014 20 42'

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July 7th, 2018 - J STD 003C WAM1 IPC New Release IPC IPC Nieuwe Release Solderability Tests for Printed Boards test methods J STD 003 J STD'

'IPC Standards Committee Reports Assembly amp Joining

July 13th, 2018 - This task group met a second day to resolve comments on criteria common to both IPC J STD 001 and Task Group completed work on IPC J STD 003C"IPC J STD 033C CN ??  
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June 30th, 2018 - ipc j std 033c cn ?????????????? ???"J STD 003C Solderability Tests for Printed Boards

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July 1st, 2018 - Document Number J STD 003C Revision Level RENUMBERED Status Current Publication Date Oct 1 2013 Page Count 27 pages'

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June 30th, 2018 - Title IPC J STD 003B Author 850 romanova Created Date 1 20 2009 11 40 18 AM'  
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**'IPC J STD 003C 2013 Solderability Tests for Printed Boards**  
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June 23rd, 2018 - J STD 003C prescribes test methods defect definitions and illustrations for assessing the solderability of printed board surface conductors attachment lands and plated through holes utilizing either tin lead or lead free solders"IPC HDBK 001F Techstreet  
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June 14th, 2018 - www ipc org onlinestore NEW IPC J STD 003C Solderability Tests for Printed Boards J STD 003C prescribes test methods defect definitions and illustrations for assessing the solderability of printed board surface conductors attachment lands and plated through holes utilizing either tin lead or lead free solders'

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'IPC EIA J STD 003 Solderability Tests for Printed Boards  
July 12th, 2018 - Document Number IPC J STD 003C WAM1 amp 2 Revision Level REVISION C AM 2 Status Current Publication Date Oct 2 2017 Page Count 48 pages'  
'J STD 003 Solderability Tests for Printed Boards  
July 8th, 2018 - J STD 003 Revision C September 2013 Complete Document Solderability Tests for Printed Boards Includes all amendments and changes through Amendment 2 September'  
'Soldering and Assembling cdn piek international  
July 5th, 2018 - Soldering and Assembling IPC 600J J STD 075 IPC 7525B J STD 020E IPC 7526 IPC 7527 IPC 2581A J STD 002D J STD 003C J STD 004B J STD 005A"*IPC J STD 005 Requirements for Soldering Pastes*  
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June 18th, 2018 - If you need to evaluate printed boards to confirm they re acceptable for assembly processes and soldering use the new J STD 003 Revision C reviewed here'  
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'**IPC J STD 003C Solderability Tests for Printed Boards**

June 24th, 2018 - BackAmendment 1 to the J STD 003C corrects editorial errors as well as adds clarifying statements to many areas of the document Released May 2014'

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